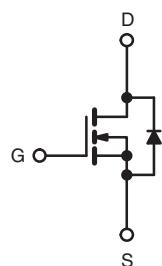


## Power MOSFET

PRODUCT SUMMARY		
V <sub>DS</sub> (V)	600	
R <sub>DS(on)</sub> (Ω)	V <sub>GS</sub> = 10 V	0.12
Q <sub>g</sub> (Max.) (nC)	320	
Q <sub>gs</sub> (nC)	85	
Q <sub>gd</sub> (nC)	160	
Configuration	Single	



N-Channel MOSFET


**RoHS\***  
COMPLIANT

### FEATURES

- Superfast Body Diode Eliminates the Need for External Diodes in ZVS Applications
- Lower Gate Charge Results in Simple Drive Requirements
- Enhanced dV/dt Capabilities Offer Improved Ruggedness
- Higher Gate Voltage Threshold Offers Improved Noise Immunity
- Compliant to RoHS Directive 2002/95/EC

### APPLICATIONS

- Zero Voltage Switching SMPS
- Telecom and Server Power Supplies
- Uninterruptible Power Supplies
- Motor Control applications

### ORDERING INFORMATION

Package	Super-247		
Lead (Pb)-free	IRFPS38N60LPbF SiHFPS38N60L-E3		
SnPb	IRFPS38N60L SiHFPS38N60L		

### ABSOLUTE MAXIMUM RATINGS (T<sub>C</sub> = 25 °C, unless otherwise noted)

PARAMETER	SYMBOL	LIMIT	UNIT
Drain-Source Voltage	V <sub>DS</sub>	600	V
Gate-Source Voltage	V <sub>GS</sub>	± 30	
Continuous Drain Current	I <sub>D</sub>	38	A
		24	
Pulsed Drain Current <sup>a</sup>	I <sub>DM</sub>	150	
Linear Derating Factor		4.3	W/C
Single Pulse Avalanche Energy <sup>b</sup>	E <sub>AS</sub>	680	mJ
Repetitive Avalanche Current <sup>a</sup>	I <sub>AR</sub>	38	A
Repetitive Avalanche Energy <sup>a</sup>	E <sub>AR</sub>	54	mJ
Maximum Power Dissipation	P <sub>D</sub>	540	W
Peak Diode Recovery dV/dt <sup>c</sup>	dV/dt	19	V/ns
Operating Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	- 55 to + 150	°C
Soldering Recommendations (Peak Temperature)	for 10 s	300 <sup>d</sup>	
Mounting Torque	6-32 or M3 screw	10	lbf · in
		1.1	N · m

#### Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 12).  
b. Starting T<sub>J</sub> = 25 °C, L = 0.91 mH, R<sub>g</sub> = 25 Ω, I<sub>AS</sub> = 38 A, dV/dt = 13 V/ns (see fig. 14a).  
c. I<sub>SD</sub> ≤ 38 A, dI/dt ≤ 630 A/μs, V<sub>DD</sub> ≤ V<sub>DS</sub>, T<sub>J</sub> ≤ 150 °C.  
d. 1.6 mm from case.

\* Pb containing terminations are not RoHS compliant, exemptions may apply

**THERMAL RESISTANCE RATINGS**

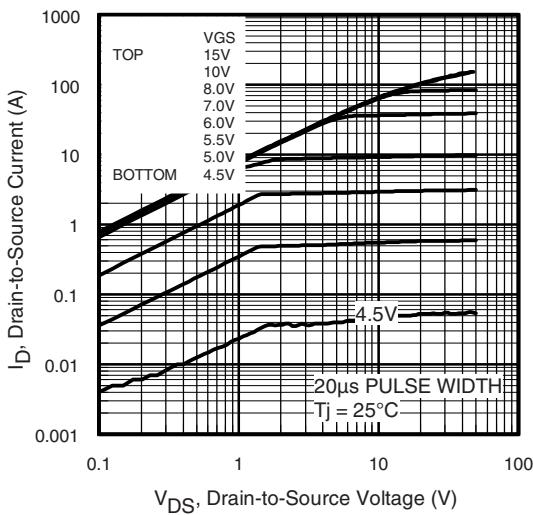
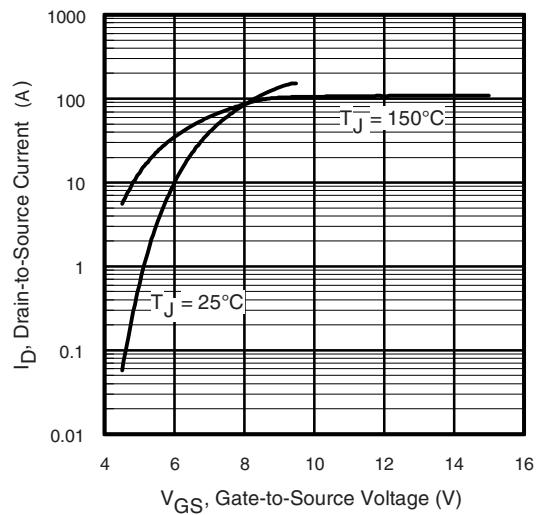
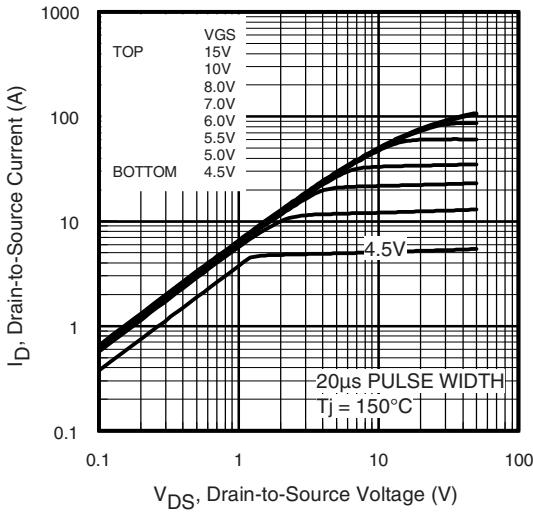
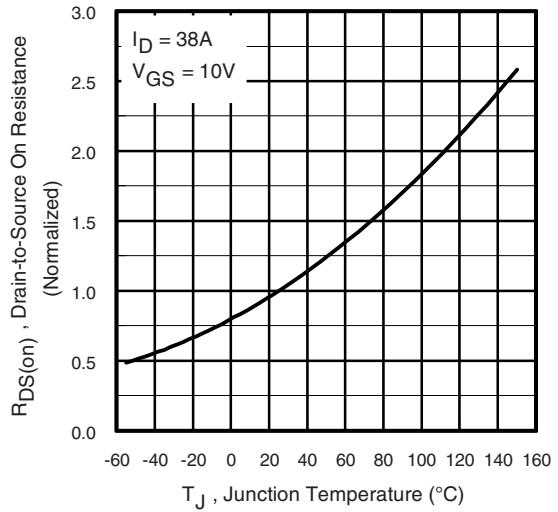
PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Maximum Junction-to-Ambient	$R_{thJA}$	-	40	°C/W
Case-to-Sink, Flat, Greased Surface	$R_{thCS}$	0.24	-	
Maximum Junction-to-Case (Drain)	$R_{thJC}$	-	0.22	

**SPECIFICATIONS** ( $T_J = 25^\circ\text{C}$ , unless otherwise noted)

PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
<b>Static</b>							
Drain-Source Breakdown Voltage	$V_{DS}$	$V_{GS} = 0 \text{ V}$ , $I_D = 250 \mu\text{A}$		600	-	-	V
$V_{DS}$ Temperature Coefficient	$\Delta V_{DS}/T_J$	Reference to $25^\circ\text{C}$ , $I_D = 1 \text{ mA}$		-	410	-	mV/°C
Gate-Source Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}$ , $I_D = 250 \mu\text{A}$		3.0	-	5.0	V
Gate-Source Leakage	$I_{GSS}$	$V_{GS} = \pm 30 \text{ V}$		-	-	$\pm 100$	nA
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = 600 \text{ V}$ , $V_{GS} = 0 \text{ V}$		-	-	50	$\mu\text{A}$
		$V_{DS} = 480 \text{ V}$ , $V_{GS} = 0 \text{ V}$ , $T_J = 125^\circ\text{C}$		-	-	2.0	mA
Drain-Source On-State Resistance	$R_{DS(on)}$	$V_{GS} = 10 \text{ V}$	$I_D = 23 \text{ A}^b$	-	0.12	0.15	$\Omega$
Forward Transconductance	$g_{fs}$	$V_{DS} = 50 \text{ V}$ , $I_D = 23 \text{ A}^b$		20	-	-	S
<b>Dynamic</b>							
Input Capacitance	$C_{iss}$	$V_{GS} = 0 \text{ V}$ , $V_{DS} = 25 \text{ V}$ , $f = 1.0 \text{ MHz}$ , see fig. 5		-	7990	-	pF
Output Capacitance	$C_{oss}$			-	740	-	
Reverse Transfer Capacitance	$C_{rss}$			-	72	-	
Effective Output Capacitance	$C_{oss \text{ eff.}}$		$V_{GS} = 0 \text{ V}$	-	350	-	
Effective Output Capacitance (Energy Related)	$C_{oss \text{ eff. (ER)}}$	$V_{DS} = 0 \text{ V to } 480 \text{ V}^c$		-	260	-	
Total Gate Charge	$Q_g$	$V_{GS} = 10 \text{ V}$	$I_D = 38 \text{ A}$ , $V_{DS} = 480 \text{ V}$ see fig. 7 and 15 <sup>b</sup>	-	-	320	nC
Gate-Source Charge	$Q_{gs}$			-	-	85	
Gate-Drain Charge	$Q_{gd}$			-	-	160	
Gate Resistance	$R_g$	$f = 1 \text{ MHz}$ , open drain		-	1.2	-	$\Omega$
Turn-On Delay Time	$t_{d(on)}$	$V_{DD} = 300 \text{ V}$ , $I_D = 38 \text{ A}$ , $R_G = 4.3 \Omega$ , $V_{GS} = 10 \text{ V}$ , see fig. 11a and 11b <sup>b</sup>		-	44	-	ns
Rise Time	$t_r$		-	130	-		
Turn-Off Delay Time	$t_{d(off)}$		-	92	-		
Fall Time	$t_f$		-	69	-		
<b>Drain-Source Body Diode Characteristics</b>							
Continuous Source-Drain Diode Current	$I_S$	MOSFET symbol showing the integral reverse p - n junction diode		-	-	38	A
Pulsed Diode Forward Current <sup>a</sup>	$I_{SM}$			-	-	150	
Body Diode Voltage	$V_{SD}$	$T_J = 25^\circ\text{C}$ , $I_S = 38 \text{ A}$ , $V_{GS} = 0 \text{ V}^b$		-	-	1.5	V
Body Diode Reverse Recovery Time	$t_{rr}$	$T_J = 25^\circ\text{C}$ , $I_F = 38 \text{ A}$		-	170	250	ns
		$T_J = 125^\circ\text{C}$ , $dI/dt = 100 \text{ A}/\mu\text{s}^b$		-	420	630	
Body Diode Reverse Recovery Charge	$Q_{rr}$	$T_J = 25^\circ\text{C}$ , $I_F = 38 \text{ A}$ , $V_{GS} = 0 \text{ V}^b$		-	830	1240	nC
		$T_J = 125^\circ\text{C}$ , $dI/dt = 100 \text{ A}/\mu\text{s}^b$		-	2600	3900	
Reverse Recovery Time	$t_{RRM}$	$T_J = 25^\circ\text{C}$		-	9.1	14	A
Forward Turn-On Time	$t_{on}$	Intrinsic turn-on time is negligible (turn-on is dominated by $L_S$ and $L_D$ )					

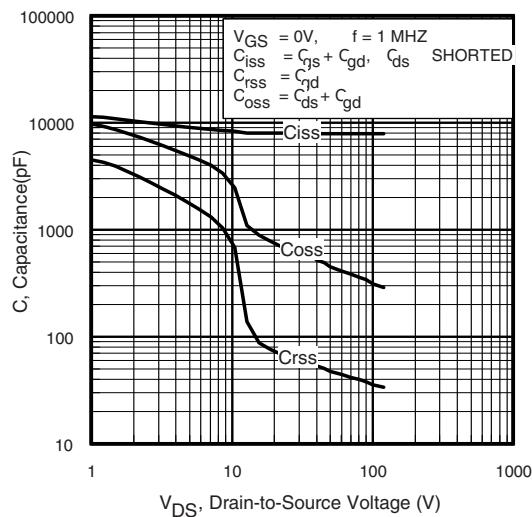
**Notes**

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 12).  
b. Pulse width  $\leq 300 \mu\text{s}$ ; duty cycle  $\leq 2 \%$ .  
c.  $C_{oss \text{ eff.}}$  is a fixed capacitance that gives the same charging time as  $C_{oss}$  while  $V_{DS}$  is rising from 0 % to 80 %  $V_{DS}$ .  
 $C_{oss \text{ eff. (ER)}}$  is a fixed capacitance that stores the same energy as  $C_{oss}$  while  $V_{DS}$  is rising from 0 % to 80 %  $V_{DS}$ .

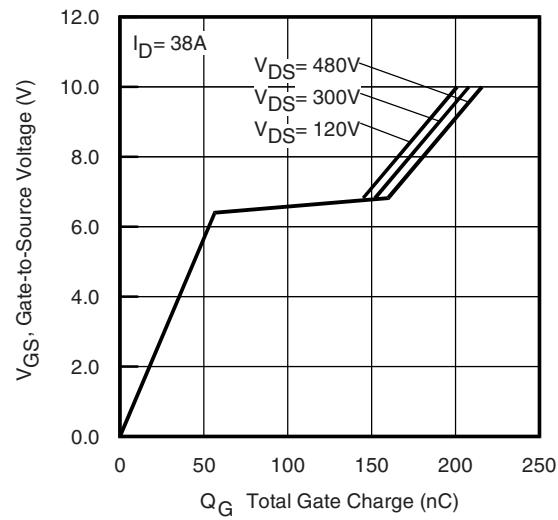
**TYPICAL CHARACTERISTICS** (25 °C, unless otherwise noted)

**Fig. 1 - Typical Output Characteristics**

**Fig. 3 - Typical Transfer Characteristics**

**Fig. 2 - Typical Output Characteristics**

**Fig. 4 - Normalized On-Resistance vs. Temperature**

# IRFPS38N60L, SiHFPS38N60L

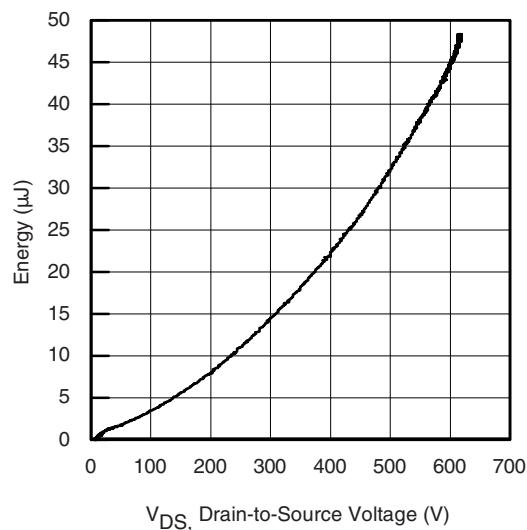
Vishay Siliconix



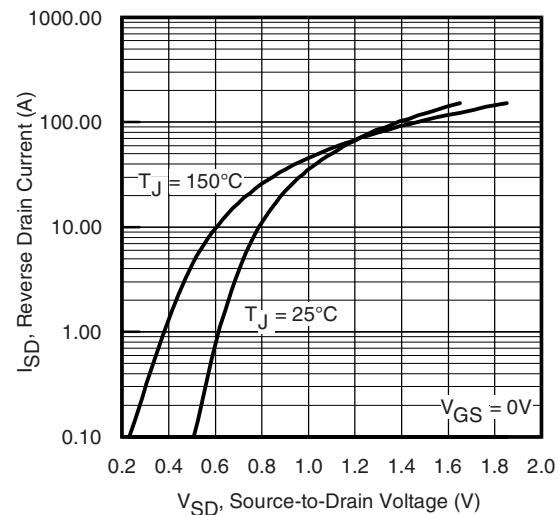
**Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage**



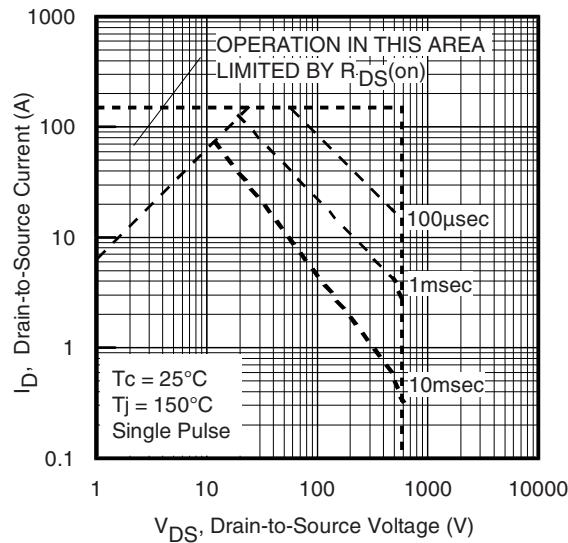
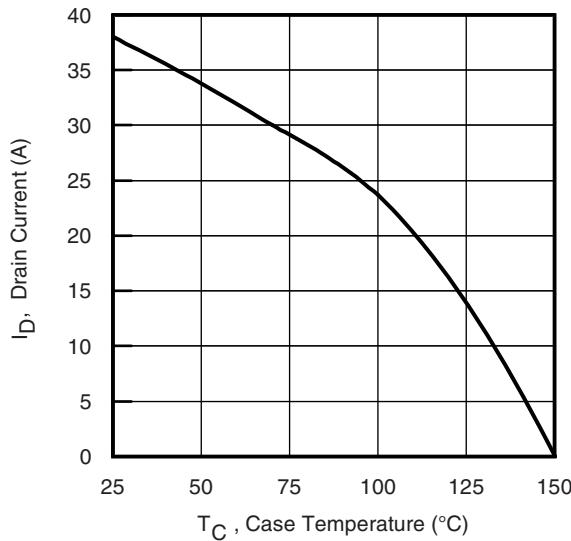
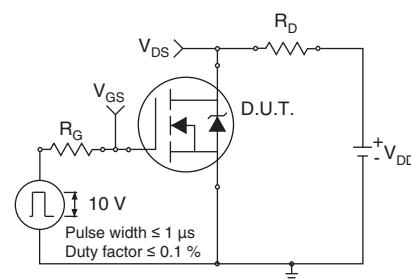
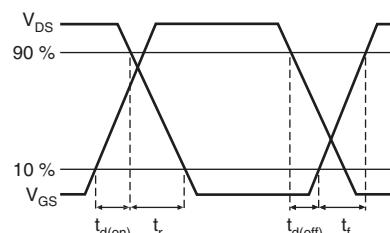
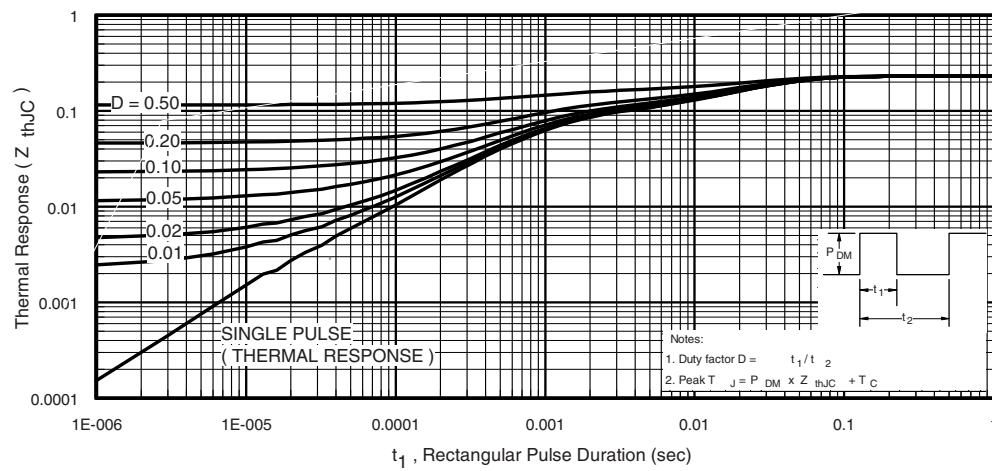
**Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage**



**Fig. 6 - Typical Output Capacitance Stored Energy vs.  $V_{DS}$**



**Fig. 8 - Typical Source-Drain Diode Forward Voltage**


**Fig. 9 - Maximum Safe Operating Area**

**Fig. 10 - Maximum Drain Current vs. Case Temperature**

**Fig. 11a - Switching Time Test Circuit**

**Fig. 11b - Switching Time Waveforms**

**Fig. 12 - Maximum Effective Transient Thermal Impedance, Junction-to-Case**

# IRFPS38N60L, SiHFPS38N60L

Vishay Siliconix

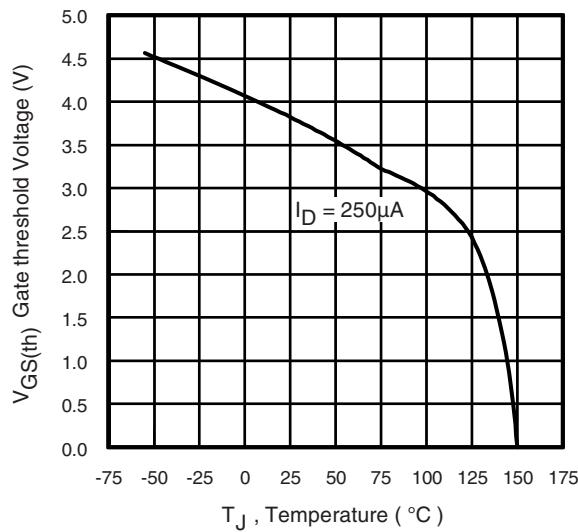


Fig. 13 - Threshold Voltage vs. Temperature

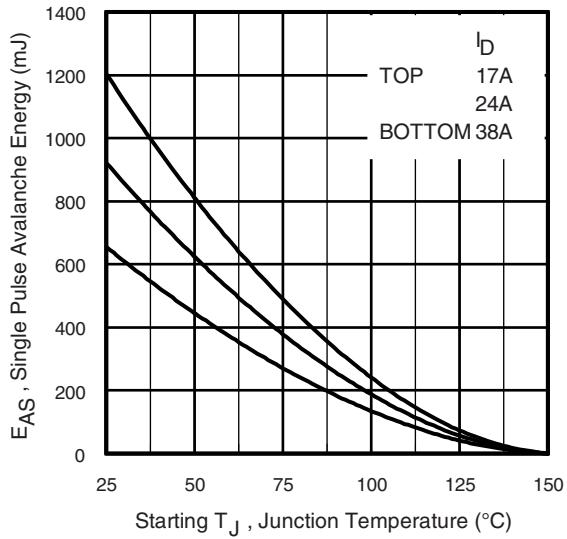


Fig. 14a - Maximum Avalanche Energy vs. Drain Current

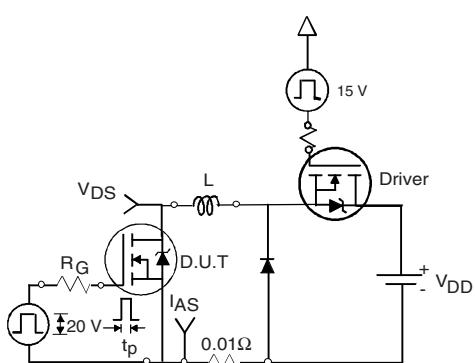


Fig. 14b - Unclamped Inductive Test Circuit

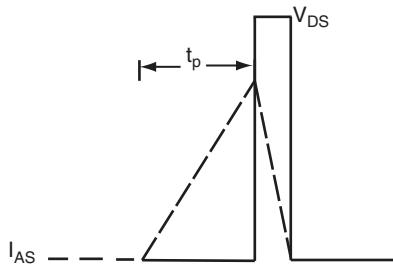


Fig. 14c - Unclamped Inductive Waveforms

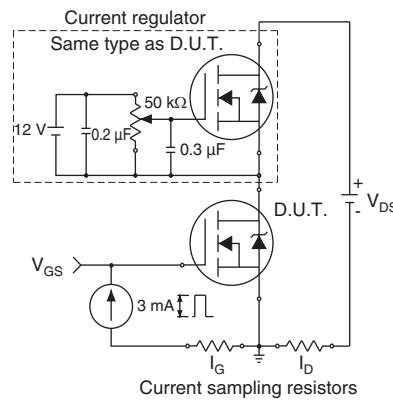


Fig. 15a - Basic Gate Charge Waveform

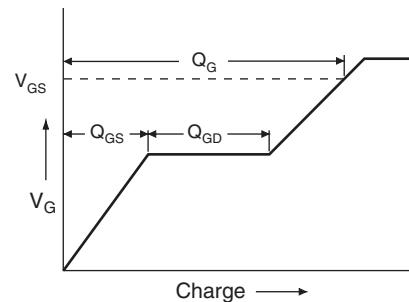
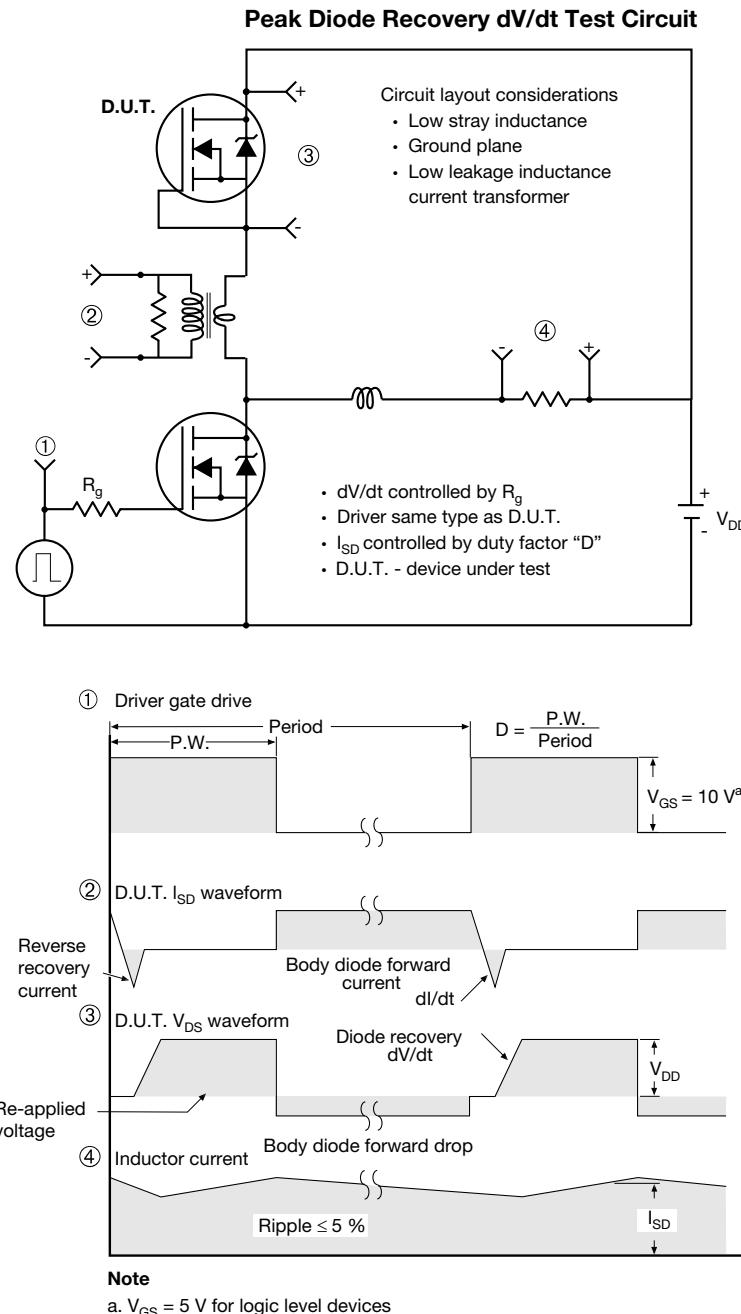
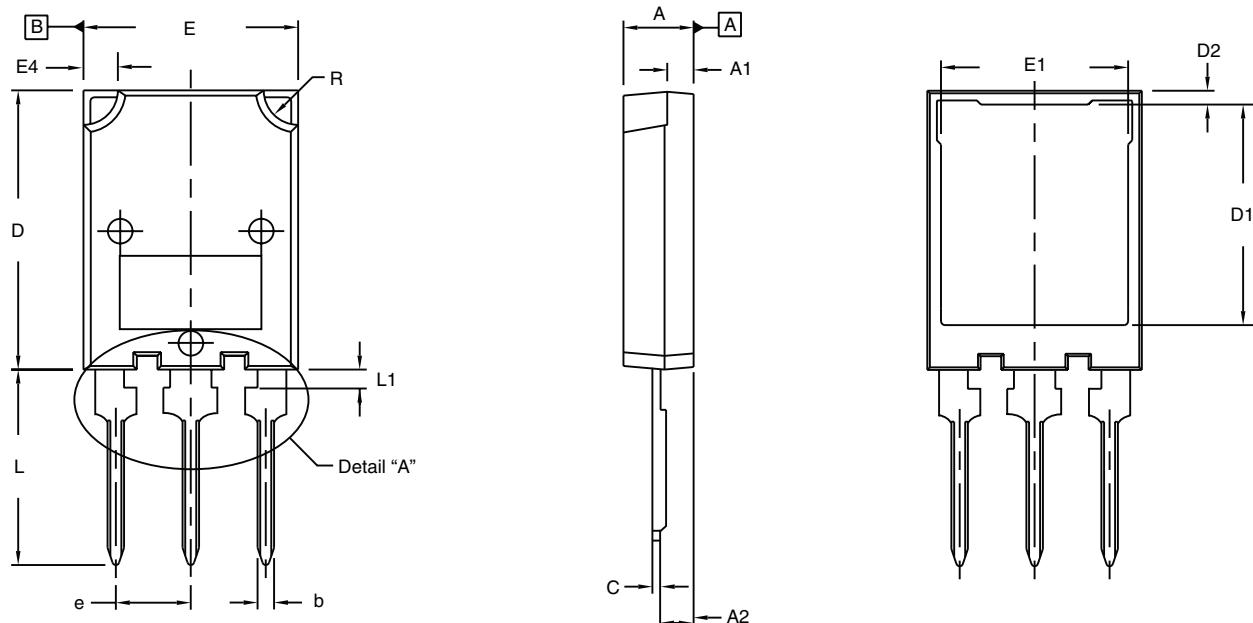


Fig. 15b - Gate Charge Test Circuit

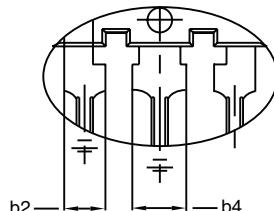
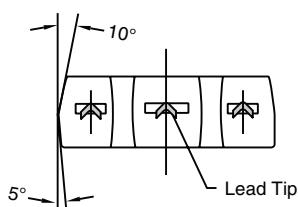

**Fig. 16 - For N-Channel**

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see [www.vishay.com/ppg?91259](http://www.vishay.com/ppg?91259).

### TO-274AA (HIGH VOLTAGE)



$\oplus$  0.10 (0.025") B A M



Detail "A"  
Scale: 2:1

DIM.	MILLIMETERS		INCHES	
	MIN.	MAX.	MIN.	MAX.
A	4.70	5.30	0.185	0.209
A1	1.50	2.50	0.059	0.098
A2	2.25	2.65	0.089	0.104
b	1.30	1.60	0.051	0.063
b2	1.80	2.20	0.071	0.087
b4	3.00	3.25	0.118	0.128
c	0.80	1.20	0.031	0.047
D	19.80	20.80	0.780	0.819

ECN: S-82247-Rev. A, 06-Oct-08

DWG: 5975

DIM.	MILLIMETERS		INCHES	
	MIN.	MAX.	MIN.	MAX.
D1	15.50	16.10	0.610	0.634
D2	0.70	1.30	0.028	0.051
E	15.10	16.10	0.594	0.634
E1	13.30	13.90	0.524	0.547
e	5.45 BSC		0.215 BSC	
L	13.70	14.70	0.539	0.579
L1	1.00	1.60	0.039	0.063
R	2.00	3.00	0.079	0.118

#### Notes

- Dimensioning and tolerancing per ASME Y14.5M-1994.
- Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outer extremes of the plastic body.
- Outline conforms to JEDEC outline to TO-274AA.



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**Vishay Intertechnology, Inc. hereby certifies that all its products that are identified as RoHS-Compliant fulfill the definitions and restrictions defined under Directive 2011/65/EU of The European Parliament and of the Council of June 8, 2011 on the restriction of the use of certain hazardous substances in electrical and electronic equipment (EEE) - recast, unless otherwise specified as non-compliant.**

**Please note that some Vishay documentation may still make reference to RoHS Directive 2002/95/EC. We confirm that all the products identified as being compliant to Directive 2002/95/EC conform to Directive 2011/65/EU.**



Компания «ЭлектроПласт» предлагает заключение долгосрочных отношений при поставках импортных электронных компонентов на взаимовыгодных условиях!

#### Наши преимущества:

- Оперативные поставки широкого спектра электронных компонентов отечественного и импортного производства напрямую от производителей и с крупнейших мировых складов;
- Поставка более 17-ти миллионов наименований электронных компонентов;
- Поставка сложных, дефицитных, либо снятых с производства позиций;
- Оперативные сроки поставки под заказ (от 5 рабочих дней);
- Экспресс доставка в любую точку России;
- Техническая поддержка проекта, помошь в подборе аналогов, поставка прототипов;
- Система менеджмента качества сертифицирована по Международному стандарту ISO 9001;
- Лицензия ФСБ на осуществление работ с использованием сведений, составляющих государственную тайну;
- Поставка специализированных компонентов (Xilinx, Altera, Analog Devices, Intersil, Interpoint, Microsemi, Aeroflex, Peregrine, Syfer, Eurofarad, Texas Instrument, Miteq, Cobham, E2V, MA-COM, Hittite, Mini-Circuits, General Dynamics и др.);

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- Подбор оптимального решения, техническое обоснование при выборе компонента;
- Подбор аналогов;
- Консультации по применению компонента;
- Поставка образцов и прототипов;
- Техническая поддержка проекта;
- Защита от снятия компонента с производства.



#### Как с нами связаться

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Электронная почта: [org@eplast1.ru](mailto:org@eplast1.ru)

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